

ABSTRACT**A SYSTEM, PROCESS AND A JIG FOR FORMING CONFORMAL EMI SHIELD ON PACKAGE-LEVEL ELECTRONICS OR A PORTION THEREOF**

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The invention provides a system for forming a conformal electromagnetic interference shield on at least one singulated electronic package (300), comprising a tray preparation module which prepares a tray (200) by mounting an electromagnetic interference tape (202) onto a frame (201), with the electromagnetic interference tape (202) covering the entirety of the frame (201), a pick and place module for placing at least one singulated electronic packages (300) onto the tray (200), a jig (100) for supporting the tray (200) having the singulated electronic packages (300), and a sputtering machine which forms a conformal electromagnetic interference shield onto the singulated electronic packages (300) through a sputtering process. The jig (100) comprises body having an arcuate surface (101), wherein the arcuate surface (101) of the jig (100) allows substantially continuous contact between the jig (100) and the electronic package (300).

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15*(Fig. 1)*

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